



VMDSEMI

**VUTJ010R10ANA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
100V	100mΩ@10V	15A
	125mΩ@4.5V	

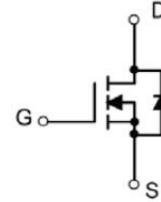
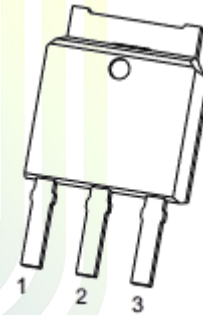


Figure 1 Symbol of VUTJ010R10ANA

## Features

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100%  $\Delta V_{DS}$  Tested

## Package Type



**TO-251-3L**

## Application

- Power switching application

Figure 2 Package Type of VUTJ010R10ANA

## Ordering Information

Product Name	Package
VUTJ010R10ANA	TO-251-3L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	15	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	60	
Single Pulse Avalanche Energy <sup>Note3</sup>	$I_{AS}$	12.5	
Single Pulse Avalanche Energy <sup>Note3</sup>	$E_{AS}$	39	mJ
Total Power Dissipation <sup>Note5</sup>	$P_D$	25	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		5		°C/W

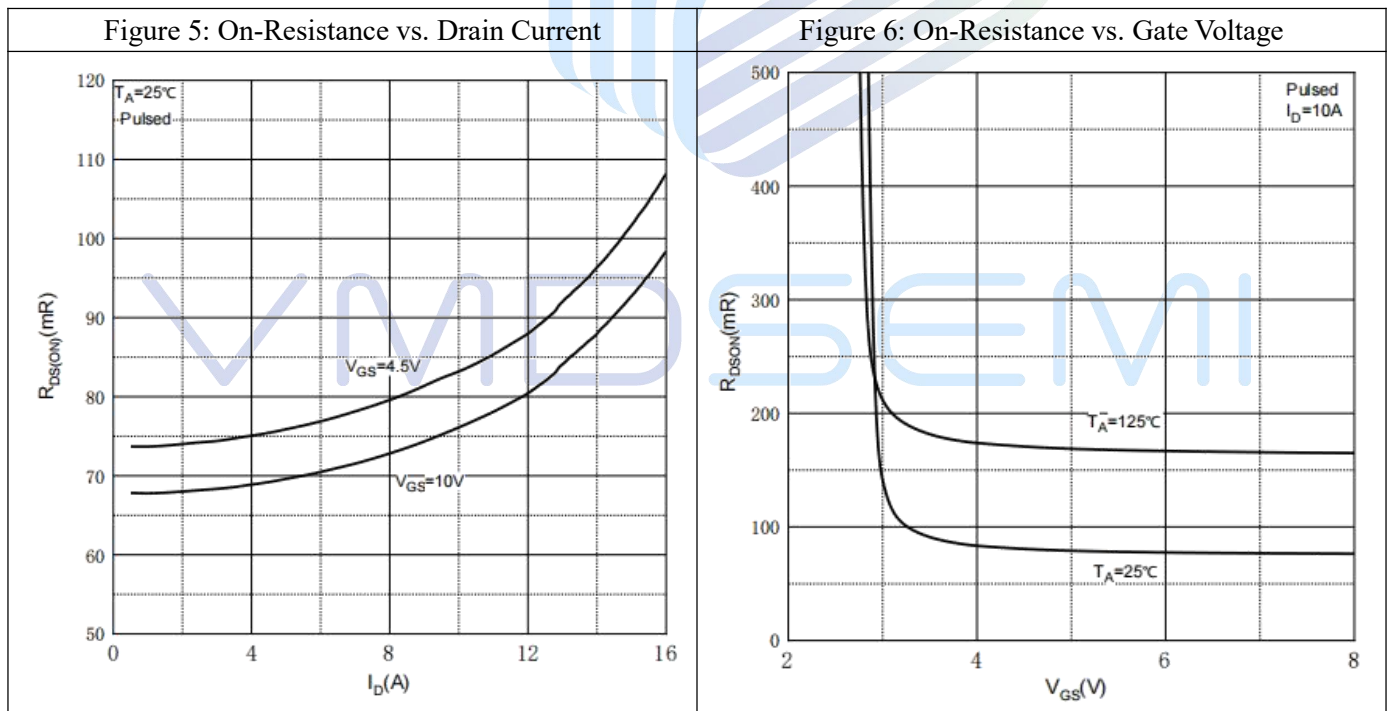
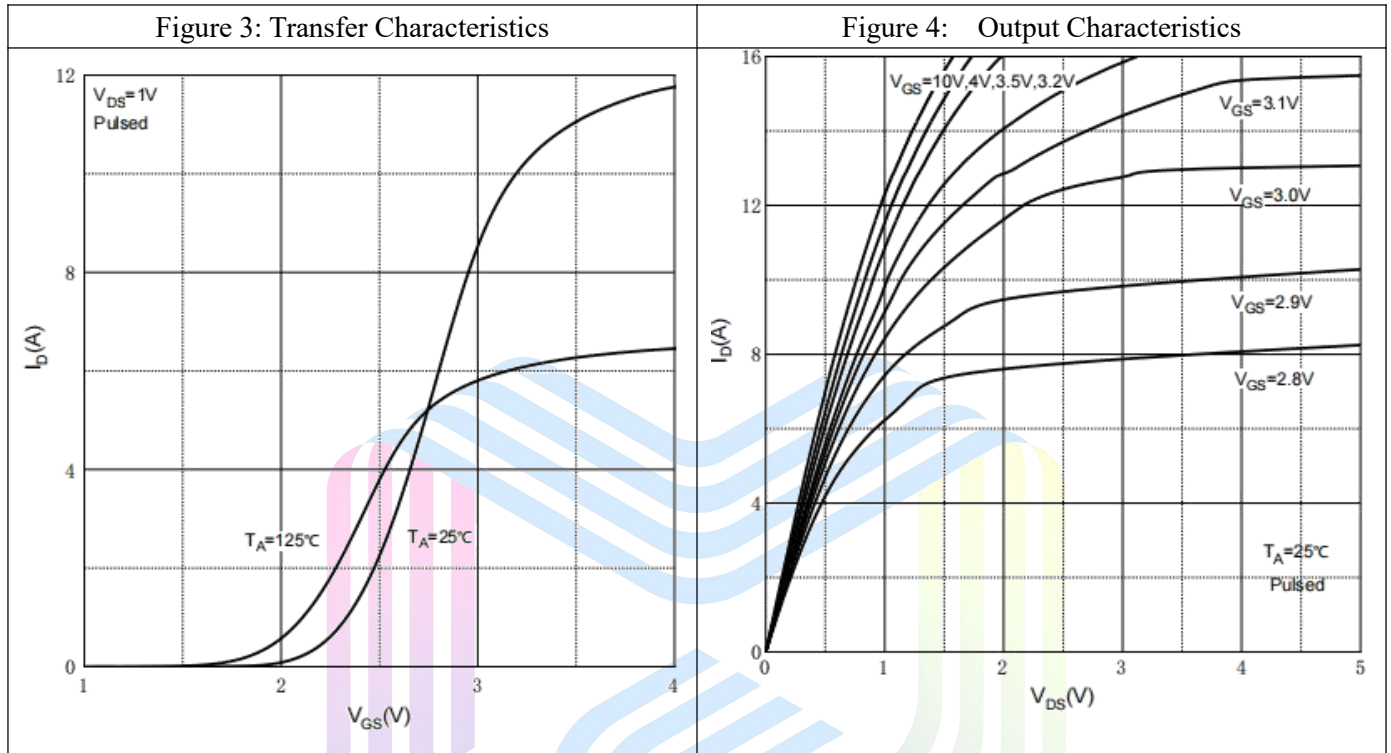
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		77	100	mΩ
		$V_{GS}=4.5V, I_D=10A$		83	125	
Forward transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=5V, I_D=10A$		16.5		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=45V$		1045		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		32.6		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		29.5		pF
Total Gate Charge	$Q_g$	$V_{DS}=45V$		25.8		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		2.9		
Gate-Drain Charge	$Q_{gd}$	$I_D=10A$		6.2		
Gate Resistance	$R_g$	$f=1MHz, \text{Open Drain}$		2.0		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		6		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		2.5		
Turn-off Delay Time	$t_{d(off)}$	$R_L=10\Omega$		18		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		2.5		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Performance Characteristics



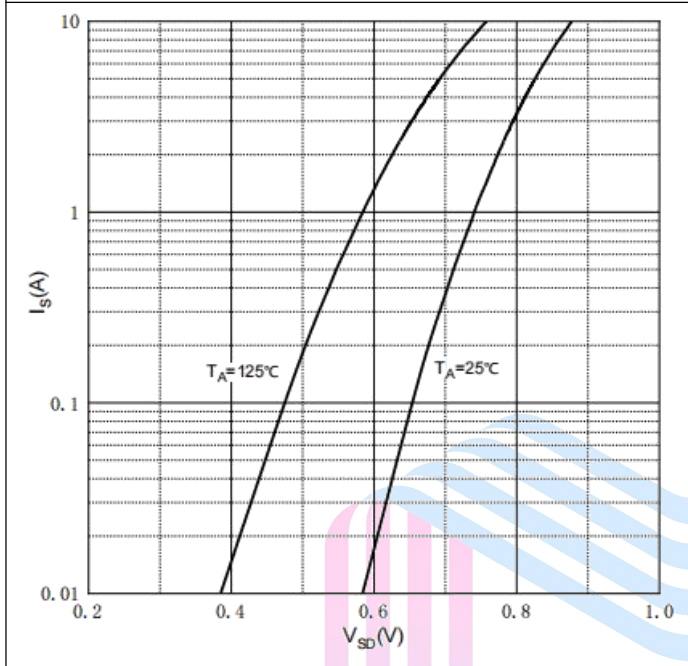
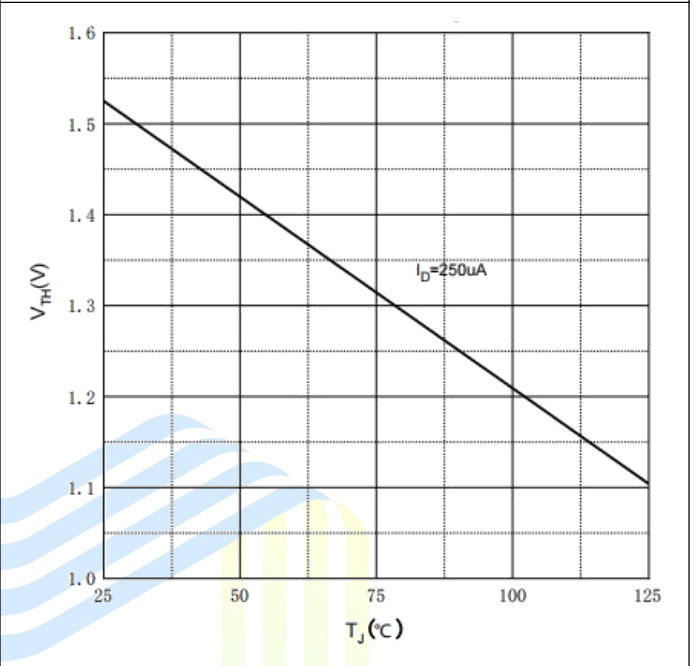
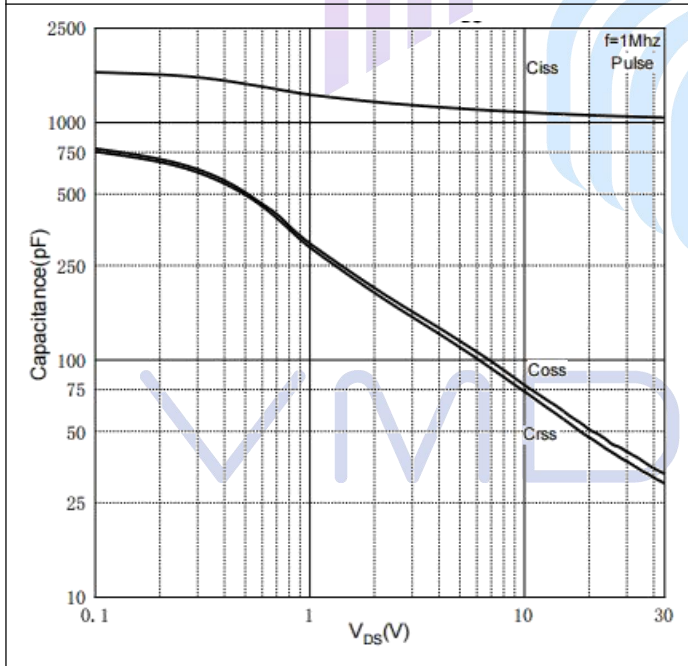
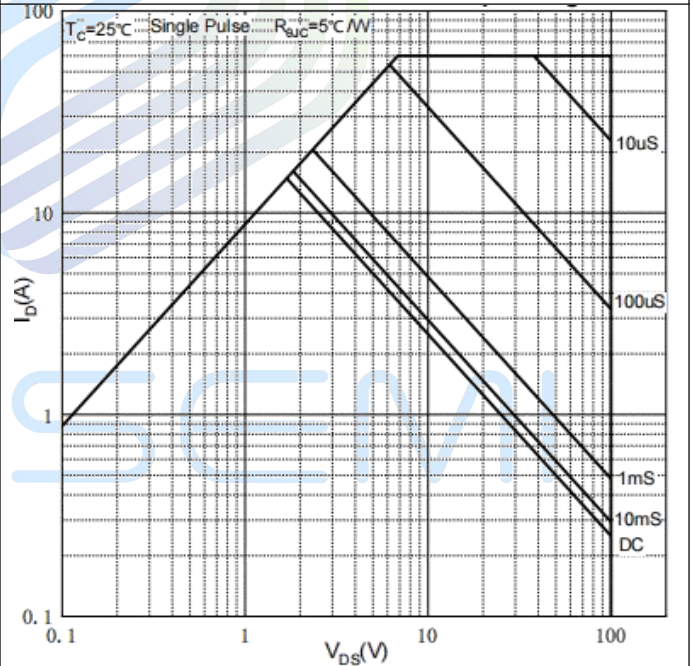
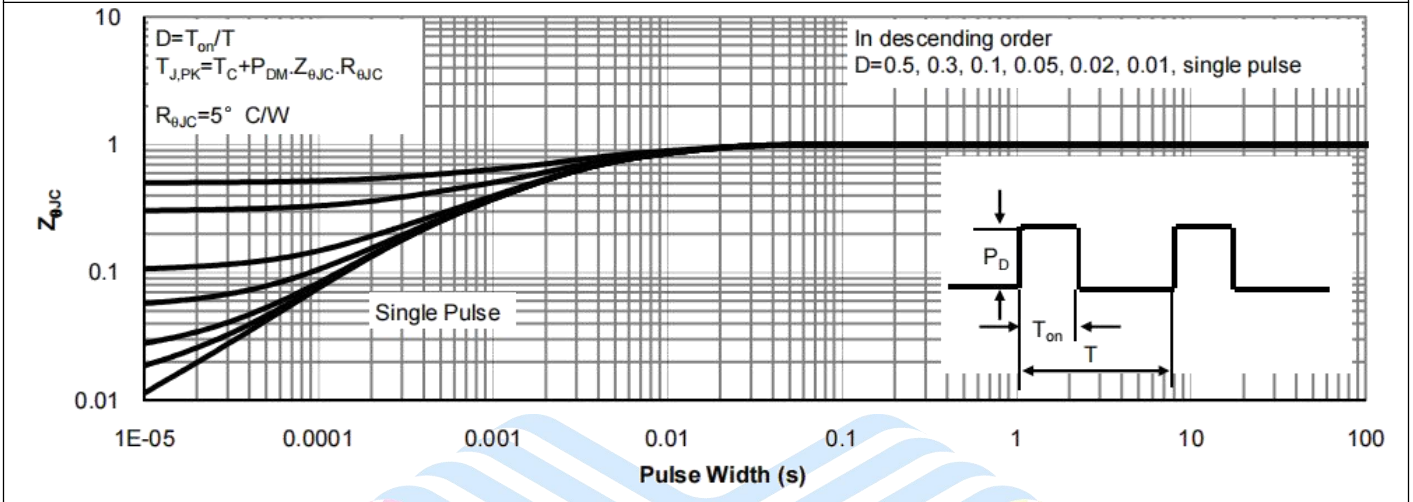
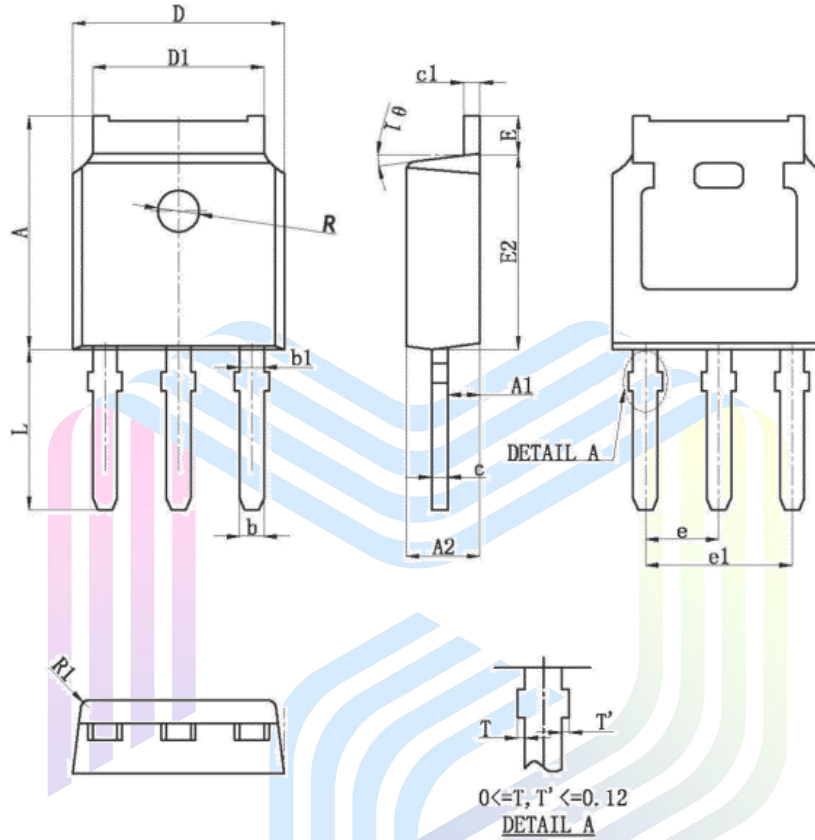
**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**


Figure 11: Normalized Maximum Transient Thermal Impedance




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**Mechanical Dimensions:**
**TO-251-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.050	7.150	0.278	0.281
A1	0.960	1.060	0.038	0.42
A2	2.250	2.350	0.089	0.93
b	0.760REF		0.030REF	
b1	1.000REF		0.040REF	
c	0.508REF		0.02REF	
c1	0.508REF		0.02REF	
D	6.550	6.650	0.258	0.262
D1	5.220	5.420	0.206	0.213
E	0.950	1.050	0.037	0.041
E2	6.050	6.150	0.238	0.242
e	2.286BSC		0.09BSC	
e1	4.472REF		0.176REF	
L	4.800	5.200	0.189	0.205
θ1	7°REF		7°REF	
R	0.250REF		0.010REF	



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